

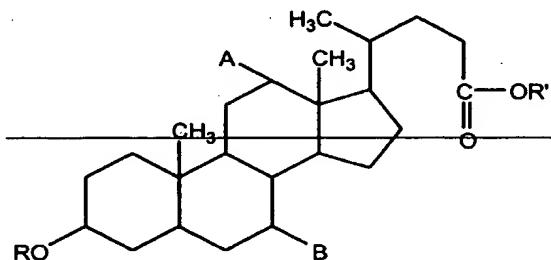
In the Claims:

Please cancel claims 2, 4-5 and 13-20 without prejudice or disclaimer.

Please amend claims 1, 3 and 7, as follows:

Claim 1 (currently amended) An additive of following Formula 1 Formulas 3-7 for a photoresist composition for a resist flow process:

Formula 1

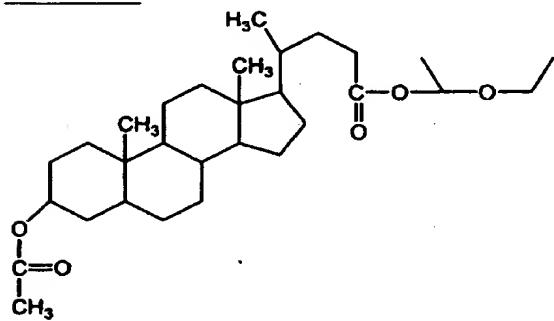


wherein, A is H or OR'',

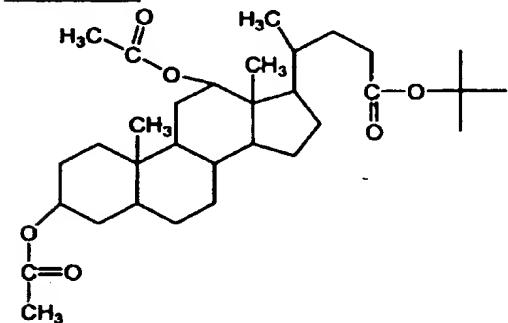
B is H or OR'', and

R, R', R'' and R''' are independently selected from the group consisting of C<sub>1</sub>-C<sub>10</sub> alkyl, C<sub>1</sub>-C<sub>10</sub> alkoxyalkyl, C<sub>1</sub>-C<sub>10</sub> alkylcarbonyl, and C<sub>1</sub>-C<sub>10</sub> alkyl containing at least one hydroxyl group (-OH).

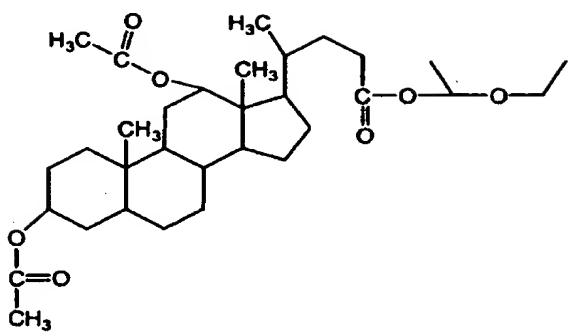
Formula 3



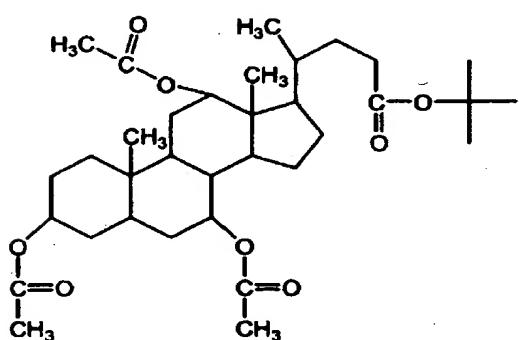
Formula 4



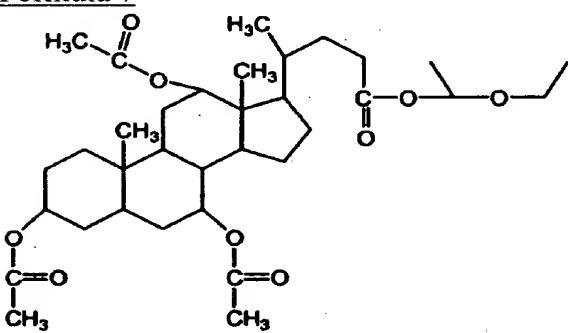
Formula 5



Formula 6



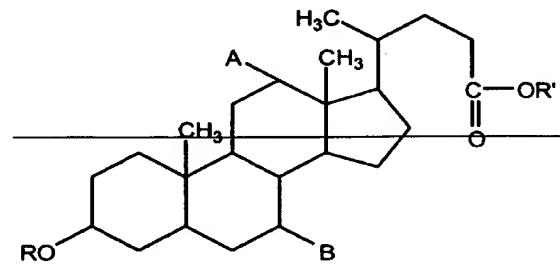
Formula 7



Claim 2 (currently canceled)

Claim 3 (currently amended) A photoresist composition comprising:  
a photoresist polymer, a photoacid generator, an additive of following Formula  
+ Formulas 3-7, and an organic solvent,

Formula 1

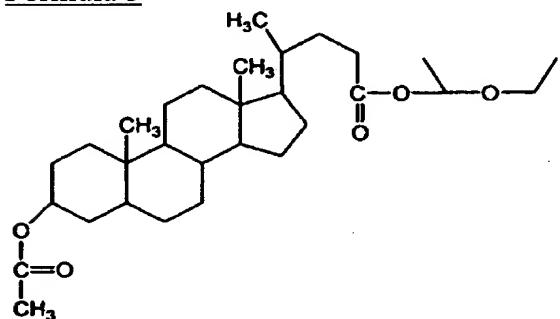


wherein, A is H or OR'',

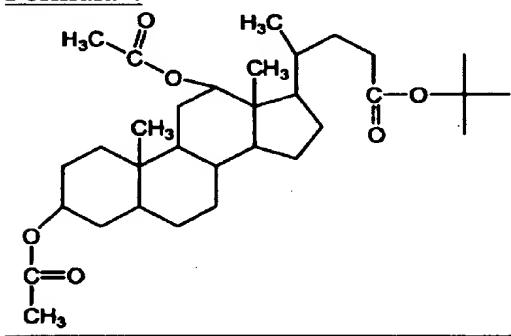
B is H or OR''', and

R, R', R'' and R''' are independently selected from the group consisting of  $\text{C}_1-\text{C}_{10}$ -alkyl,  $\text{C}_1-\text{C}_{10}$ -alkoxyalkyl,  $\text{C}_1-\text{C}_{10}$ -alkylcarbonyl, and  $\text{C}_1-\text{C}_{10}$ -alkyl containing at least one hydroxyl group (-OH).

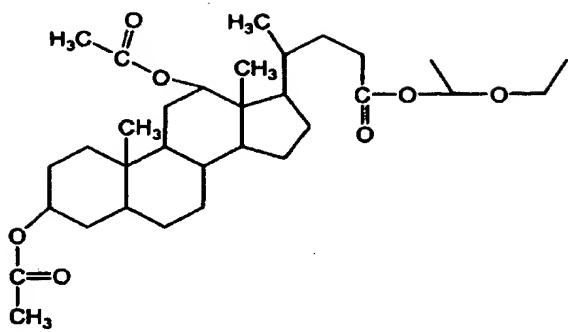
Formula 3



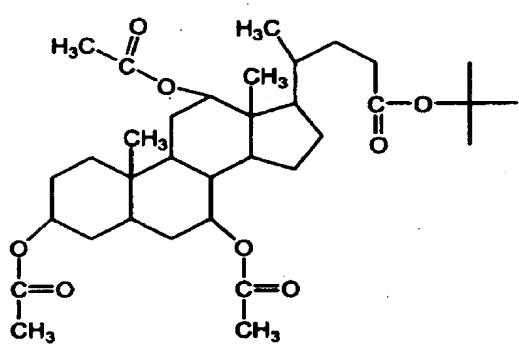
Formula 4



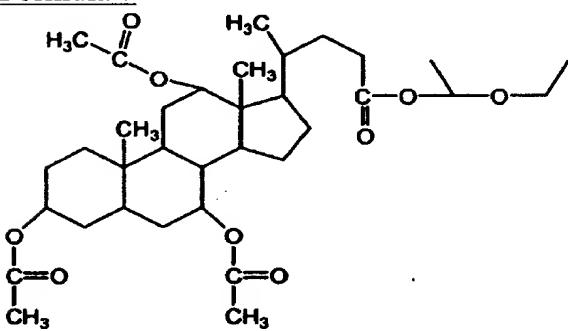
Formula 5



Formula 6



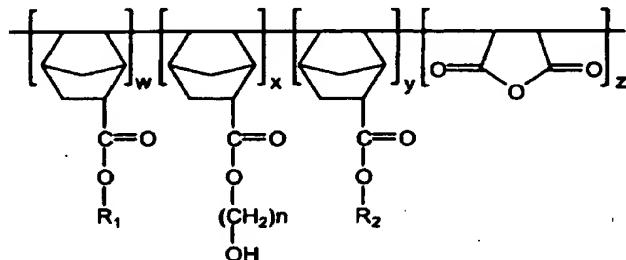
Formula 7



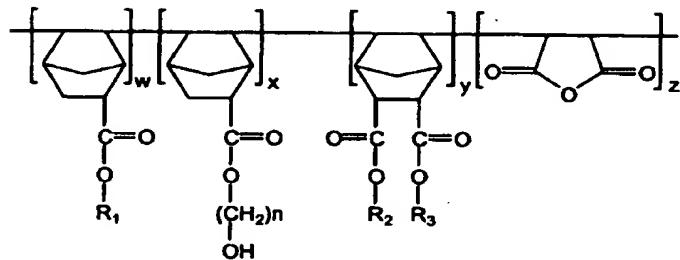
Claims 4-5 (currently canceled)

Claim 6 (original) The photoresist composition of claim 3 wherein the photoresist polymer is a compound of following Formulas 8 or 9:

Formula 8



Formula 9



wherein, R<sub>1</sub> is an acid labile protecting group;

R<sub>2</sub> is hydrogen;

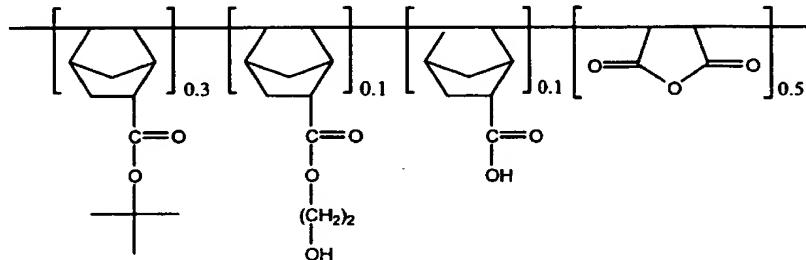
R<sub>3</sub> is hydrogen, selected from the group consisting of C<sub>1</sub>-C<sub>10</sub> alkyl, C<sub>1</sub>-C<sub>10</sub> alkoxyalkyl, and C<sub>1</sub>-C<sub>10</sub> alkyl containing at least one hydroxyl group (-OH);

n is an integer from 1 to 5; and

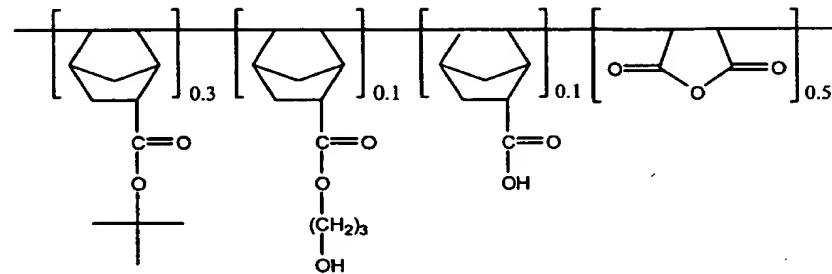
w, x, y and z individually denote the mole ratio of each monomer, preferably with proviso that w + x + y = 50mol%, and z is 50mol%.

Claim 7 (currently amended) The photoresist composition of claim 6 wherein the photoresist polymer is selected from the group consisting of compounds of following Formulas 10 to 13:

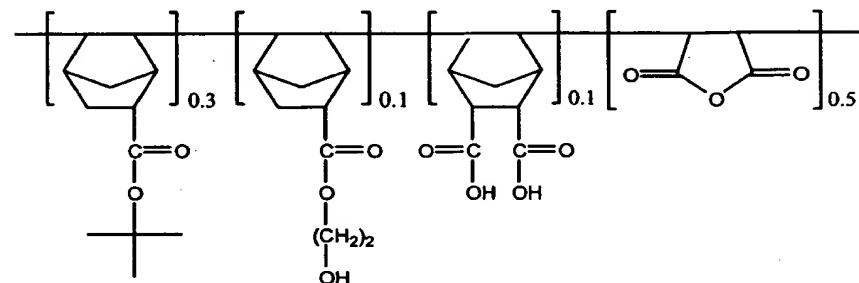
Formula 10



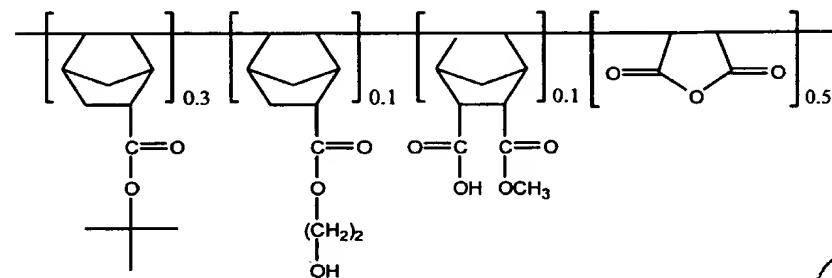
Formula 11



Formula 12



Formula 13



Claim 8 (original) The photoresist composition of claim 3 wherein the additive is present in an amount ranging from about 1 to about 70% by weight of the photoresist polymer.

Claim 9 (original) The photoresist composition of claim 3 wherein said photoacid generator is selected from the group consisting of diphenyl iodide hexafluorophosphate, diphenyl iodide hexafluoroarsenate, diphenyl iodide hexafluoroantimonate, diphenyl p-methoxyphenyl triflate, diphenyl p-toluenyl triflate, diphenyl p-isobutylphenyl triflate, diphenyl p-tert-butylphenyl triflate, triphenylsulfonium hexafluororosphosphate, triphenylsulfonium hexafluoroarsenate,

triphenylsulfonium hexafluoroantimonate, triphenylsulfonium triflate, dibutyl naphthylsulfonium triflate, and mixtures thereof.

Claim 10 (original) The photoresist composition of claim 3 wherein the photoacid generator is present in an amount ranging from about 0.01 to about 10% by weight of the photoresist polymer.

Claim 11 (original) The photoresist composition of claim 3 wherein the organic solvent is selected from the group consisting of propylene glycol methyl ether acetate, ethyl lactate, methyl 3-methoxypropionate, ethyl 3-ethoxypropionate and cyclohexanone.

Claim 12 (original) The photoresist composition of claim 3 wherein the organic solvent is present in a range of from about 100 % to about 1000% by weight of the photoresist polymer.

Claims 13-20 (currently canceled)